

June 12-14, 2019, Hong Kong, China

## CALL FOR PAPERS

The Asia-Pacific International Conference on Lightning is an excellent platform for both worldwide academics and professionals to present and discuss latest findings in the field of lightning discharge and lightning protection. The 11<sup>th</sup> Asia-Pacific International Conference on Lightning (APL2019) will be held on June 12 -14, 2019 in Hong Kong, organized by **The Hong Kong Polytechnic University** and **APL2019 Organizing Committee**. **APL2019** will continue along the line of previous conferences held in Beijing (2003), Seoul (2004), Tokyo (2005), Guangzhou (2007), Jeju (2008), Yokohama (2009), Chengdu (2011), Seoul (2013), Nagoya (2015) and Krabi (2017), respectively.

### TECHNICAL SUBJECT AREAS

1. Lightning Discharge
2. Lightning Detection and Warning Systems
3. Lightning Electromagnetic Pulse (LEMP) and Lightning-Induced Effects
4. Lightning Attachment
5. Lightning Down-Conductors and Earthing
6. Lightning Protection of Power Systems
7. Lightning Protection of Railways and Vehicles
8. Lightning Protection of Electronic Systems
9. Lightning Protection of Renewable Energy Systems and Smart Grids
10. Lightning Testing Standards or Guidelines of Lightning Protection
11. Practical and Specific Lightning Protection Problems
12. Lightning Safety
13. Special Session: Lightning and other Transients in Substations

### IMPORTANT DATES

Preliminary paper submission in PDF (deadline): ~~Feb. 28, 2019~~ **Mar. 7, 2019**  
 Notification of Acceptance: **Mar. 31, 2019**  
 Final paper submission in PDF (deadline): **Apr. 30, 2019**

### SUBMISSION OF PAPER

Please submit original papers by ~~Feb. 28, 2019~~ **Mar. 7, 2019** to [www.apl2019.org](http://www.apl2019.org). Your manuscript should be prepared according to the detailed instructions for authors for this conference (the template will be provided), and should be submitted in PDF format. The manuscript length should be 4 to 6 pages. Author's kits will be available at the website: [www.apl2019.org](http://www.apl2019.org). Each paper will be peer-reviewed and notification of acceptance/rejection will be sent by **Mar. 31, 2019**. The final paper should be submitted online by **Apr. 30, 2019**. The official language of the conference will be English. All printed materials, oral presentations and discussions will be in English. All papers submitted and presented on APL2019 will be sent to IEEE Xplore Digital Library.

### REGISTRATION

All participants, including speakers, are expected to register and pay the registration fee of HK\$3900 (on or before **May 1, 2019**) or HK\$4700 (after May 1, 2019 or on site), which includes conference materials, welcome dinner and banquet.

### CONTACT

Conference website: [www.apl2019.org](http://www.apl2019.org)  
 Secretary: ZS804, Block Z, The Hong Kong Polytechnic Univ., Hong Kong  
 E-mail: [oc.apl2019@gmail.com](mailto:oc.apl2019@gmail.com) / [oc@apl2019.org](mailto:oc@apl2019.org)

### STEERING COMMITTEE

- Prof. J. He, Chairman (China)
- Prof. Y. Baba, Vice Chairman (Japan)
- Prof. B. Zhang, Secretary (China)
- Prof. Patrick Y. Du (Hong Kong, China)
- Prof. Z. Fu (China)
- Dr. S. Gu (China)
- Mr. Z. A. Hartono (Malaysia)
- Prof. U. Kumar (India)
- Prof. B. H. Lee (Korea)
- Dr. K. Lee (Korea)
- Mr. M. Sato (Japan)
- Prof. K. Yamamoto (Japan)
- Prof. S. Yokoyama (Japan)
- Prof. P. Yutthagowith (Thailand)
- Prof. Y. Zhang (China)

### ORGANIZING COMMITTEE

- Prof. Patrick Y. Du, Chairman (Hong Kong, China)
- Prof. M. Chen, Co-Chairman (Hong Kong, China)
- Mr. Z. Qin, Secretary (Hong Kong, China)
- Prof. B. Zhang (China)
- Dr. H. Chen (China)
- Mr. B. Li (Hong Kong, China)
- Mr. G. Zhang (Hong Kong, China)
- Miss R. Qi (Hong Kong, China)
- Mr. S. Ng (Hong Kong, China)
- Prof. Y. Zhang (China)

### TECHNICAL PROGRAM COMMITTEE

- Prof. M. Chen, Chairman (Hong Kong, China)
- Prof. Y. Baba, Co-Chairman (Japan)
- Prof. Z. Fu, Co-Chairman (China)
- Prof. J. W. Woo, Co-Chairman (Korea)
- Prof. P. Yutthagowith, Co-Chairman (Thailand)

### ORGANIZER

- The Hong Kong Polytechnic University
- APL2019 Local Organizing Committee

### TECHNICAL SPONSOR

- IEEE Hong Kong Section